

## Poster-Session

### Setup and Applications of Large Area Flash Lamp Annealing

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Flash Lamp Annealing (FLA) is an upcoming technology for ultra-fast thermal processing of large substrate areas. In comparison to conventional furnace processing, its benefits are high energy efficiency, small machine footprint and high throughput. Recent developments put this technology from pilot-scale level to an industrial level enabling a reproducible and effective large area treatment. Thus, various applications show the potential of substituting furnace annealing processes by FLA or even introduce the FLA technology as an annealing step into a process chain where annealing has previously not been possible or economic.

At Fraunhofer FEP an in-line FLA tool is installed, giving the possibility to investigate the FLA process for different applications. Furthermore, the FLA process itself is also focus of research, as there are different questions on long-term stability, economics and scalability to be answered.